

We carry PEK-162C1

Substrate: Bare-Si

RESIST Film Thickness: 2.0um / 3.0um

Bake: SB 100C60s/PEB 90C60s

TARC; AQUATARVIII (90°C/60sec FT430Å)

Exposure: Nikon NSR-2005EX12B NA0.55, σ 0.8 conv.

Photomask: Binary

Dev.: TMAH 2.38%, w/o surfactant, 23C

60s puddle (FT2.0um) / 30s+60s puddle (FT3.0um)

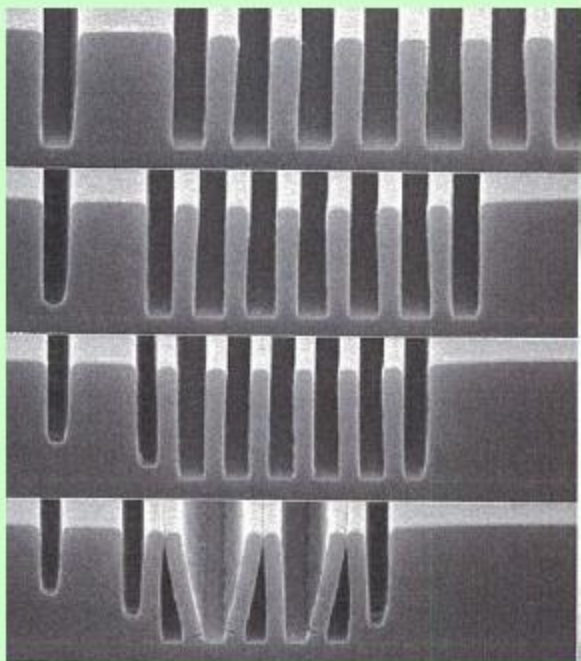
For our lab, use AZ300MIF developer (0.26N, not 0.24N)

We do not carry Aquatar TARC, Use AR2 for underlayer.

Develop 60s puddle, gentle agitation.

PEK-162 pattern profile and Resolution data F.T. 2.0um

Dark FIELD 28.5mJ/cm²



Mask size

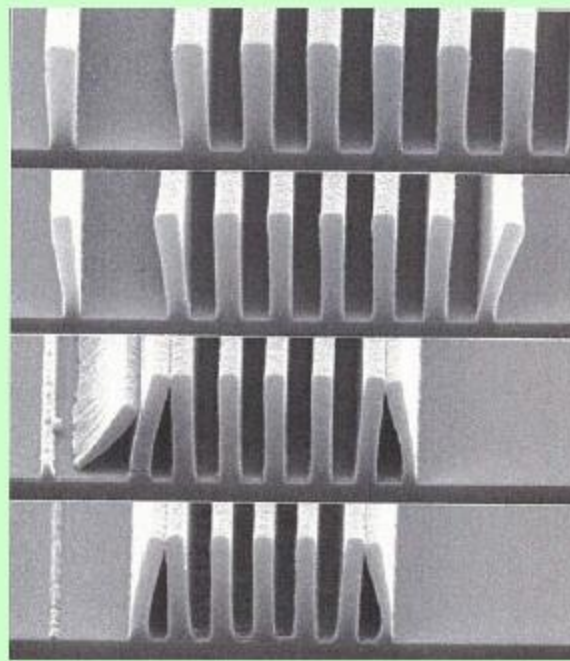
500nmL/S

400nmL/S

375nmL/S

350nmL/S

Bright FIELD 27mJ/cm²



PEK-162 pattern profile and Resolution data F.T. 3.0um

